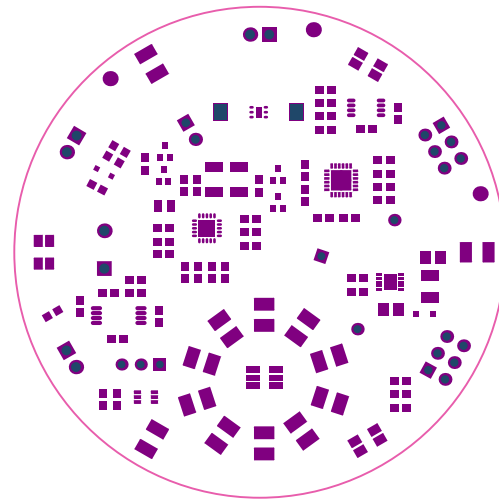
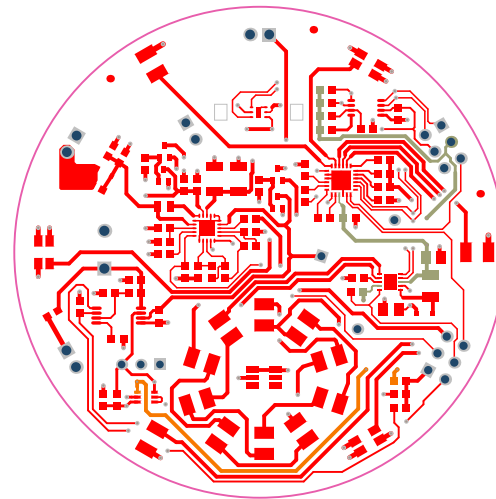


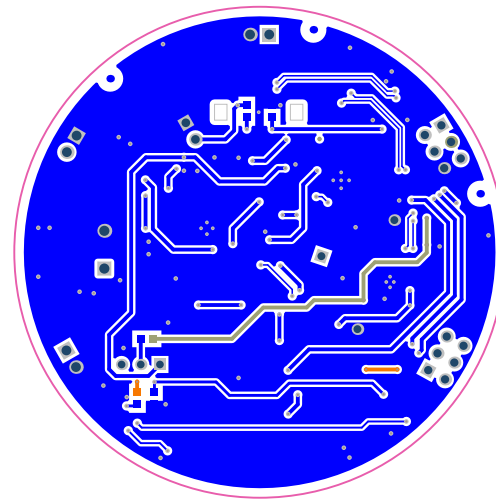
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00998	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00998		
PLOT NAME = Top Overlay	GENERATED : 5/19/2017	3:06:53 PM	TEXAS INSTRUMENTS



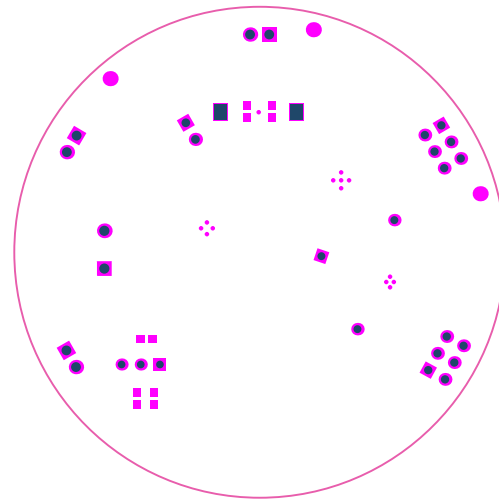
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00998	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00998		
PLOT NAME = Top Solder Mask	GENERATED : 5/19/2017 3:06:54 PM	TEXAS INSTRUMENTS	



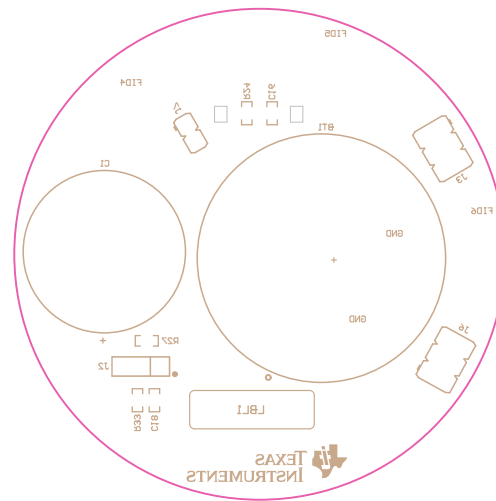
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00998	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00998		
PLOT NAME = Top Layer	GENERATED : 5/19/2017 3:06:55 PM	TEXAS INSTRUMENTS	



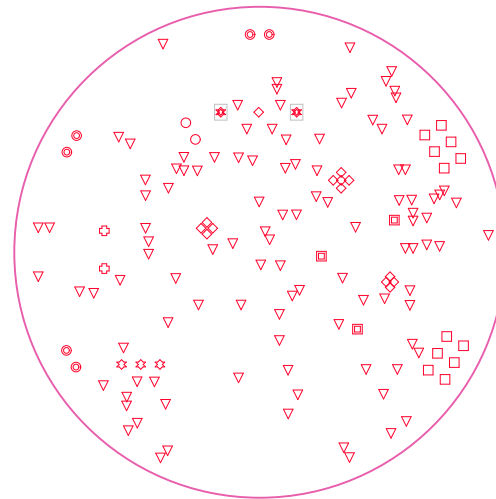
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00998	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00998		
PLOT NAME = Bottom Layer	GENERATED : 5/19/2017 3:06:55 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00998	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00998		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/19/2017 3:06:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00998	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00998		
PLOT NAME = Bottom Overlay	GENERATED : 5/19/2017	3:06:57 PM	TEXAS INSTRUMENTS

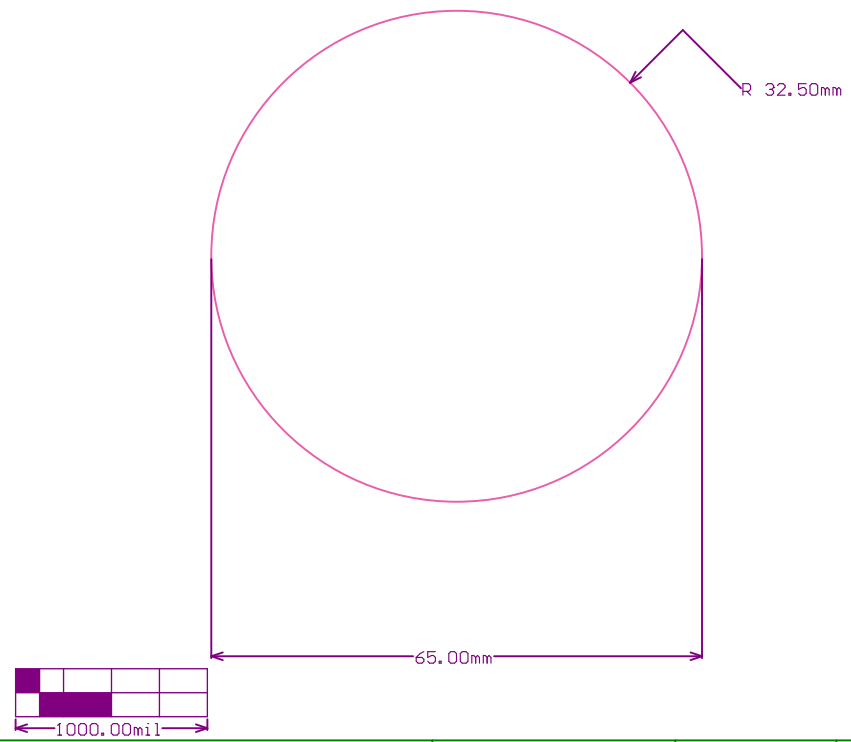


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Length
◇	14	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	-
▽	109	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	-
☆	3	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	-
■	3	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	-
□	12	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	-
○	2	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	-
●	6	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	-
⊗	2	53.15mil (1.350mm)	PTH	Round	Top Layer - Bottom Layer	-
⊛	2	65.00mil (1.651mm)	NPTH	Rectangle	Top Layer - Bottom Layer	82.00mil (2.083mm)
	153 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length * Tool Size = Slot length as defined in the PCB layout

FOR 7.87MIL DRILL +0/-7.87MIL
FOR 12MIL DRILL +0/-12MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00998	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00998		
PLOT NAME = Drill Drawing	GENERATED : 5/19/2017	3:06:58 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00998	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = MI Board Outline	TID #: TIDA-00998		
PLOT NAME = Board Dimensions	GENERATED : 5/19/2017	3:06:59 PM	TEXAS INSTRUMENTS

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